

Title (en)  
PANE WITH ELECTRIC CONNECTION ELEMENT AND CONNECTING ELEMENT ATTACHED THERETO

Title (de)  
SCHEIBE MIT ELEKTRISCHEM ANSCHLUSSELEMENT UND DARAN ANGEBRACHTEM VERBINDUNGSELEMENT

Title (fr)  
DISQUE DOTÉ D'UN ÉLÉMENT DE RACCORDEMENT ÉLECTRIQUE ET ÉLÉMENT DE LIAISON DISPOSÉ DESSUS

Publication  
**EP 3292737 B1 20210317 (DE)**

Application  
**EP 16722581 A 20160501**

Priority  
• EP 15166354 A 20150505  
• EP 2016059716 W 20160501

Abstract (en)  
[origin: WO2016177653A1] The invention relates to a wafer having at least one electric connection element, at least comprising: a substrate (1), an electrically conductive structure (2) on an area of the substrate (1), a bridge-like electric connection element (3), comprising a bridge area (3a) and at least two soldering legs (3b), which are connected by a soldering material (4) to an area of the electrically conductive structure (2), and an electric connecting element (5) fitted to the connection element (3), wherein the connecting element (5) is fitted to the surface (I) of the bridge area (3a) that faces the substrate (1) or is fitted to the surface (II) of the bridge area (3a) that faces away from the substrate (1) and is led around the bridge area (3a), such that the connecting element rests on the surface (I) of the bridge area (3a) that faces the substrate (1), wherein the difference between the melting temperature of the material of the connection element (3) and the melting temperature of the material of the connecting element (5) is greater than 200 °C, and wherein the connecting element (5) is fitted to the connection element (3) by means of a welded connection.

IPC 8 full level  
**H01Q 1/12** (2006.01); **H05B 3/84** (2006.01); **H05K 1/03** (2006.01)

CPC (source: CN EA EP KR US)  
**H01Q 1/02** (2013.01 - EA US); **H01Q 1/1271** (2013.01 - KR); **H01Q 1/1278** (2013.01 - EA US); **H01Q 1/3275** (2013.01 - EA US);  
**H01Q 1/3283** (2013.01 - EA US); **H01R 4/023** (2013.01 - CN EA US); **H01R 4/029** (2013.01 - CN EA); **H01R 12/65** (2013.01 - CN EA);  
**H01R 43/0235** (2013.01 - CN EA); **H05B 3/08** (2013.01 - EA KR); **H05B 3/84** (2013.01 - EA EP KR US); **H01Q 1/1271** (2013.01 - EA EP US);  
**H05B 2203/016** (2013.01 - EA EP KR US)

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**WO 2016177653 A1 20161110**; BR 112017021128 A2 20180703; CA 2984056 A1 20161110; CA 2984056 C 20200324;  
CN 106463845 A 20170222; CN 106463845 B 20201106; EA 034685 B1 20200306; EA 201792377 A1 20180430; EP 3292737 A1 20180314;  
EP 3292737 B1 20210317; ES 2870138 T3 20211026; HU E054283 T2 20210830; JP 2018520458 A 20180726; JP 6576467 B2 20190918;  
KR 101999468 B1 20190711; KR 20170134616 A 20171206; MX 2017013923 A 20180115; MX 368692 B 20191011; PL 3292737 T3 20210802;  
US 10700408 B2 20200630; US 2018083339 A1 20180322

DOCDB simple family (application)  
**EP 2016059716 W 20160501**; BR 112017021128 A 20160501; CA 2984056 A 20160501; CN 201680000814 A 20160501;  
EA 201792377 A 20160501; EP 16722581 A 20160501; ES 16722581 T 20160501; HU E16722581 A 20160501; JP 2017557392 A 20160501;  
KR 20177031829 A 20160501; MX 2017013923 A 20160501; PL 16722581 T 20160501; US 201615562891 A 20160501